

# TG-CJ-20-20-6-PF Ceramic Heat Spreader



## Features

Large contact area  
Low weight  
High breakdown voltage  
Excellent heat spreader  
Custom shapes possible

## Applications

LED/ NotebookPC/ M/B/ PowerTransistor/ PowerModule/CPU/ ChipIC

Main Component			Al <sub>2</sub> O <sub>3</sub>
Physical Property	Density	g/cm <sup>3</sup>	3.66
	Water Absorption	%	0.002
	Sinter Temperature	°C	1700
	Acid resistance	mg/cm <sup>3</sup>	≤ 0.2
	Alkali	mg/cm <sup>3</sup>	≤ 0.2
Mechanical Property	Mohs Hardness	HV	9
	Bend Strength	Mpa	≥ 610
	Compression Intensity	Mpa	≥ 620
Thermal Property	Maximum working temperature	°C	1400
	Refractoriness	°C	≥ 1500
	thermal expansion coefficient	( 1 x 10 <sup>-6</sup> )mm/°C	7.8 ~ 8.3
	Thermal Shock resistance	T(°C)	200
	Thermal Conductivity	W/m.k	40 ~ 51
Electrical Property	Resisting rate of Volume	Ω. °C	1016
	DC breakdown strength	KV/mm	15.2 ~ 16.7
	Insulation Breakdown Intensity	KV/mm	18
	Dielectric Constant (1MHz)	(E)	10
	Dielectric Dissipation	(tg o)	0.4*10 <sup>-3</sup>